



## CALL FOR PAPERS

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The International Conference on Microelectronics has been held in numerous countries across the Middle East and Asia for the past 26 years. The 27th edition of the conference will be held in Casablanca, Morocco. IEEE-ICM 2015 will include oral, poster sessions and tutorials given by experts on state-of-the-art topics. The regular technical program will run for three days. In addition, tutorial sessions will be held on the first day of the conference. Papers are solicited in, but not limited to, the following topics:

#### Circuits and Systems

- Analog and RF circuit design techniques
- Digital signal and data processing
- Wireless communication systems
- Nonlinear circuits
- System on chip (SoCs)
- VLSI for signal and image processing
- Integrated antenna and front-end co-design
- Signal processing in communication
- Digital image processing applications
- Biomedical circuits and systems

#### CAD Tools and Design

- Simulation (process, device, circuit, logic, timing, function)
- Layout (placement, routing, floor planning, symbolic, ERC, DRC)
- Silicon optimization
- Parallel embedded systems
- Testing: Formal verification
- CAD for FPGAs
- High-level synthesis tools
- Design for testability

#### Micro/Nanoelectronics

- Device characterization and modelling
- Device physics and novel structures
- Process technology, CMOS, BJT,
- BiCMOS, GaAs
- Reliability and failure analysis
- Optoelectronics
- MEMS devices
- Packaging and surface mount technology

#### Special Sessions

- Smart sensors and sensor networks
- Biomedical
- Renewable energy sources
- Complex systems

Prospective authors are invited to submit full-length (four pages) papers, in IEEE format, using the guidelines in the authors' info. Only electronic submissions will be accepted via the online submission system. Accepted papers will be published in the electronic conference proceedings (flash memory stick) and submitted for posting to IEEE Xplore.

#### Deadlines

Full paper submission:

**20 September Anywhere on Earth GMT-12)**

**11 October 2015**

Notification of acceptance:

**25 October 2015**

Camera-ready submission:

**8 November 2015**

